

END OF LIFE

International
IR Rectifier

IRF7452QPbF

- Advanced Process Technology
- Ultra Low On-Resistance
- N Channel MOSFET
- Surface Mount
- Available in Tape & Reel
- 150°C Operating Temperature
- Lead-Free

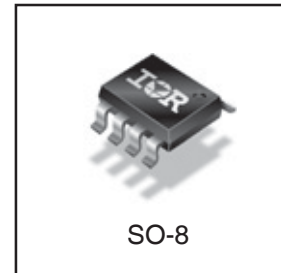
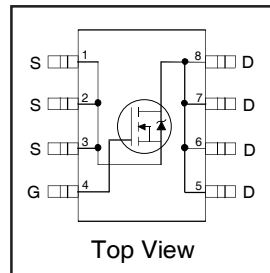
Description

These HEXFET® Power MOSFET's in SO-8 package utilize the latest processing techniques to achieve extremely low on-resistance per silicon area. Additional features of these HEXFET Power MOSFET's are a 150°C junction operating temperature, fast switching speed and improved repetitive avalanche rating. These benefits combine to make this design an extremely efficient and reliable device for use in a wide variety of applications.

The efficient SO-8 package provides enhanced thermal characteristics making it ideal in a variety of power applications. This surface mount SO-8 can dramatically reduce board space and is also available in Tape & Reel.

HEXFET® Power MOSFET

V_{DS}	$R_{DS(on)}$ max	I_D
100V	0.060 Ω	4.5A



Base part number	Orderable part number	Package Type	Standard Pack		EOL Notice	Replacement Part Number
			Form	Quantity		
IRF7452QPbF	IRF7452QTRPbF	SO-8	Tape and Reel	4000	EOL 529	Please search the EOL part number on IR's website for guidance
	IRF7452QPbF	SO-8	Tube	95	EOL 529	

Absolute Maximum Ratings

	Parameter	Max.	Units
I_D @ $T_A = 25^\circ\text{C}$	Continuous Drain Current, V_{GS} @ 10V	4.5	A
I_D @ $T_A = 70^\circ\text{C}$	Continuous Drain Current, V_{GS} @ 10V	3.6	
I_{DM}	Pulsed Drain Current ①	36	
P_D @ $T_A = 25^\circ\text{C}$	Power Dissipation	2.5	W
	Linear Derating Factor	0.02	W/°C
V_{GS}	Gate-to-Source Voltage	± 30	V
dv/dt	Peak Diode Recovery dv/dt ③	3.5	V/ns
T_J	Operating Junction and	-55 to + 150	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	

Typical SMPS Topologies

- Telecom 48V input DC-DC with Half Bridge Primary or Datacom 28V input with Passive Reset Forward Converter Primary

Notes ① through ⑥ are on page 8

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Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	100	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.11	—	V/°C	Reference to 25°C , $I_D = 1mA$ ⑥
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.060	Ω	$V_{GS} = 10V, I_D = 2.7A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	3.0	—	5.5	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
I_{DSS}	Drain-to-Source Leakage Current	—	—	25	μA	$V_{DS} = 100V, V_{GS} = 0V$
		—	—	250		$V_{DS} = 80V, V_{GS} = 0V, T_J = 150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 24V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -24V$

Dynamic @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
g_{fs}	Forward Transconductance	3.4	—	—	S	$V_{DS} = 50V, I_D = 2.7A$
Q_g	Total Gate Charge	—	33	50	nC	$I_D = 2.7A$
Q_{gs}	Gate-to-Source Charge	—	7.3	11		$V_{DS} = 80V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	16	24		$V_{GS} = 10V, \text{④}$
$t_{d(on)}$	Turn-On Delay Time	—	9.5	—	ns	$V_{DD} = 50V$
t_r	Rise Time	—	11	—		$I_D = 2.7A$
$t_{d(off)}$	Turn-Off Delay Time	—	16	—		$R_G = 6.0\Omega$
t_f	Fall Time	—	13	—		$V_{GS} = 10V, \text{④}$
C_{iss}	Input Capacitance	—	930	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	300	—		$V_{DS} = 25V$
C_{rss}	Reverse Transfer Capacitance	—	84	—		$f = 1.0MHz$
C_{oss}	Output Capacitance	—	1370	—		$V_{GS} = 0V, V_{DS} = 1.0V, f = 1.0MHz$
C_{oss}	Output Capacitance	—	170	—		$V_{GS} = 0V, V_{DS} = 80V, f = 1.0MHz$
$C_{oss \text{ eff.}}$	Effective Output Capacitance	—	280	—		$V_{GS} = 0V, V_{DS} = 0V \text{ to } 80V \text{ ⑤}$

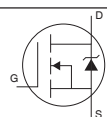
Avalanche Characteristics

	Parameter	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy②	—	200	mJ
I_{AR}	Avalanche Current①	—	4.5	A
E_{AR}	Repetitive Avalanche Energy①	—	0.25	mJ

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Maximum Junction-to-Ambient⑥	—	50	°C/W

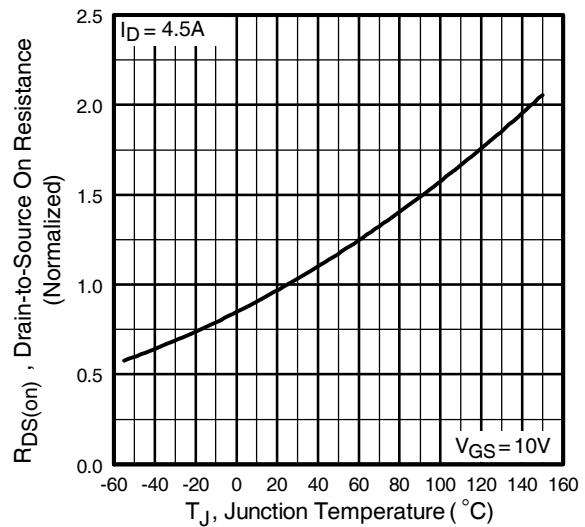
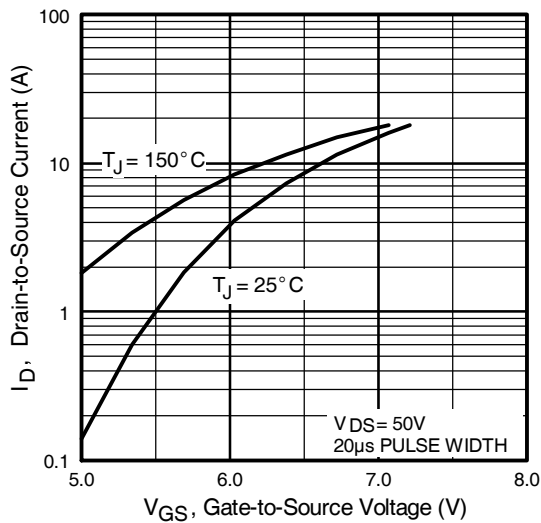
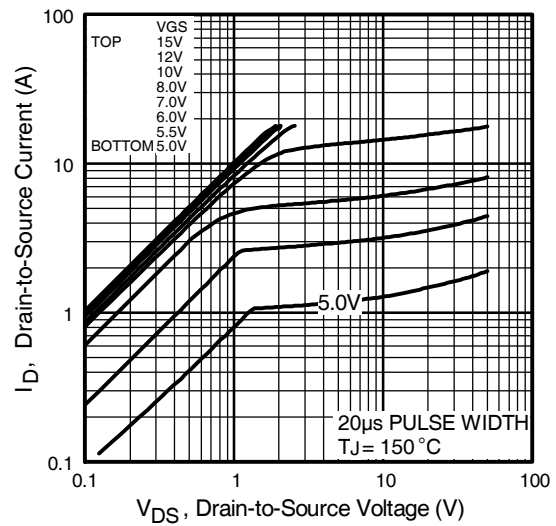
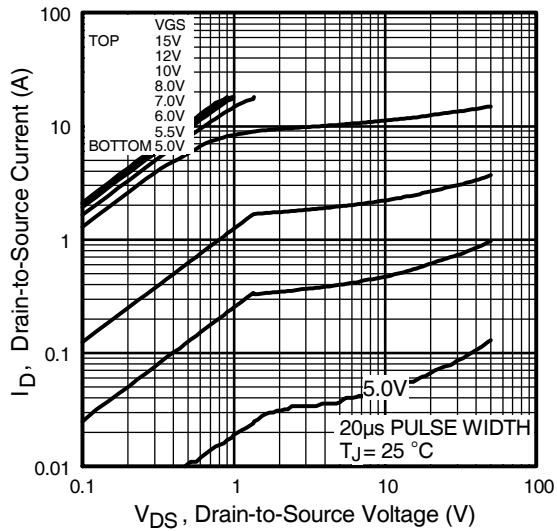
Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	2.3	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	36		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}, I_S = 2.7A, V_{GS} = 0V$ ④
t_{rr}	Reverse Recovery Time	—	77	120	ns	$T_J = 25^\circ\text{C}, I_F = 2.7A$
Q_{rr}	Reverse Recovery Charge	—	270	410	nC	$di/dt = 100A/\mu s$ ④

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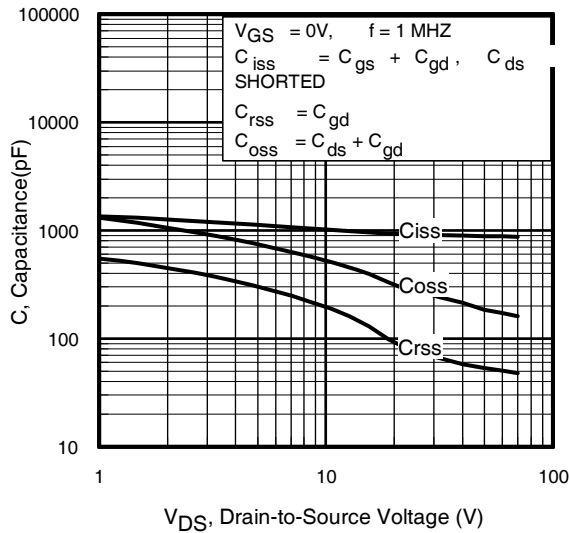


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

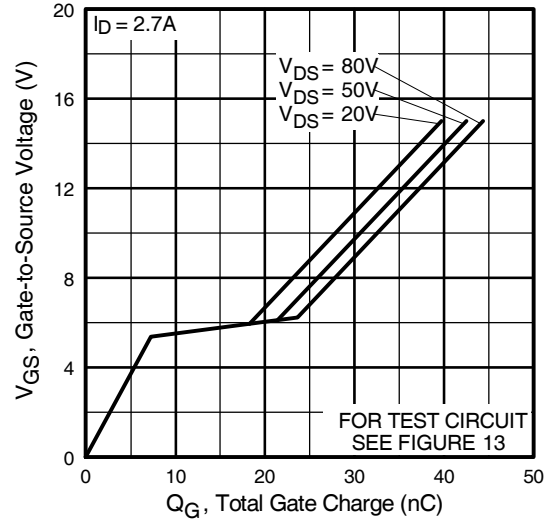


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

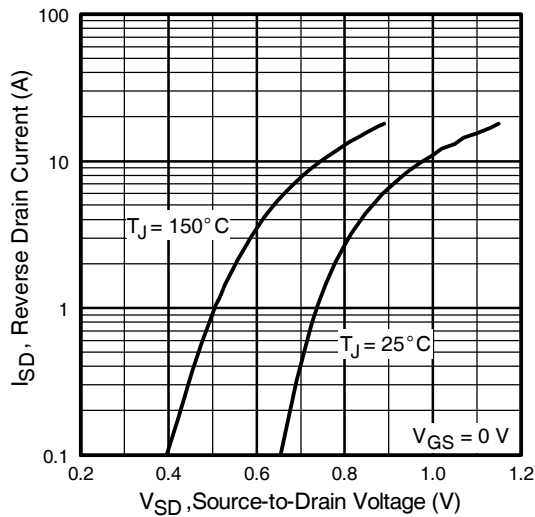


Fig 7. Typical Source-Drain Diode Forward Voltage

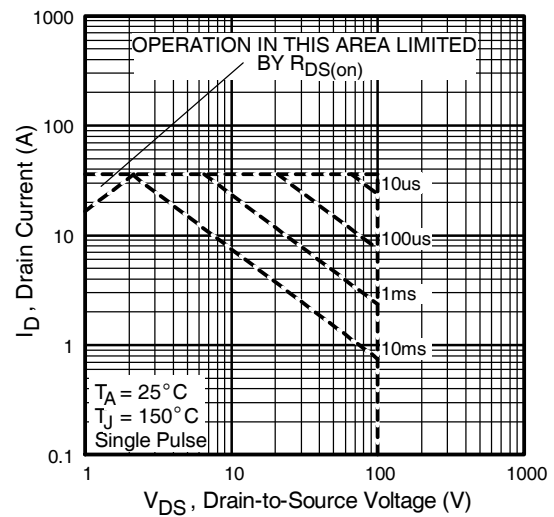


Fig 8. Maximum Safe Operating Area

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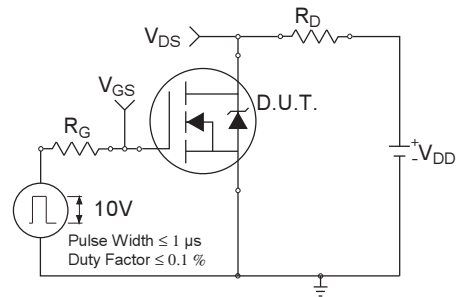
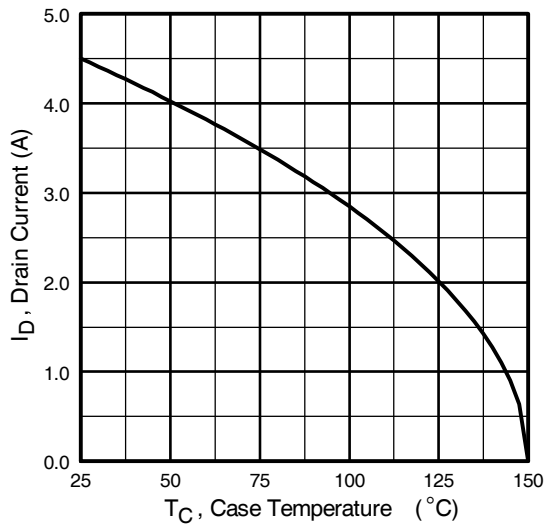


Fig 10a. Switching Time Test Circuit

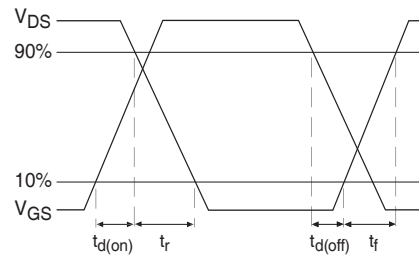


Fig 10b. Switching Time Waveforms

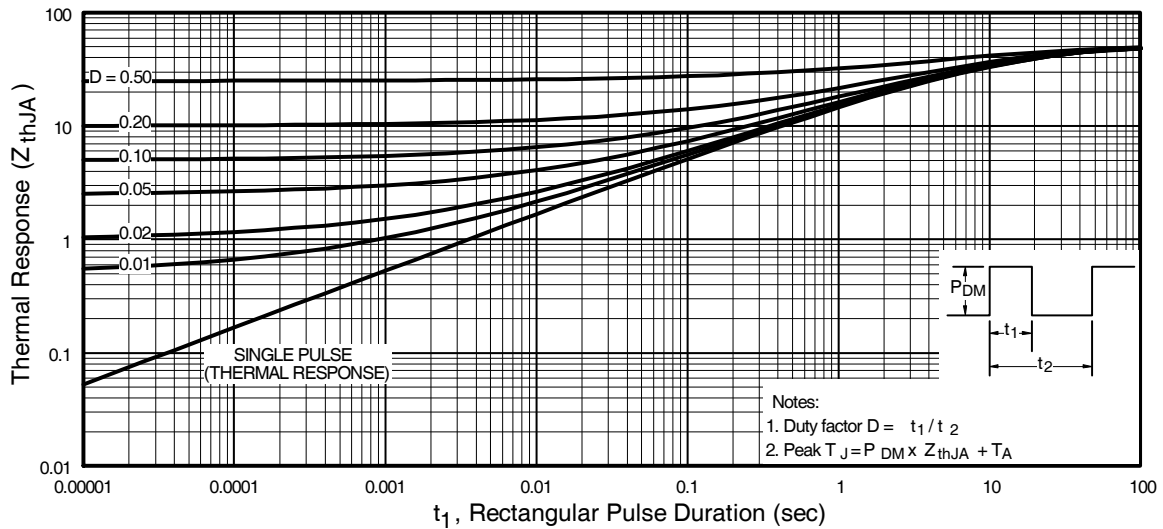


Fig 10. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

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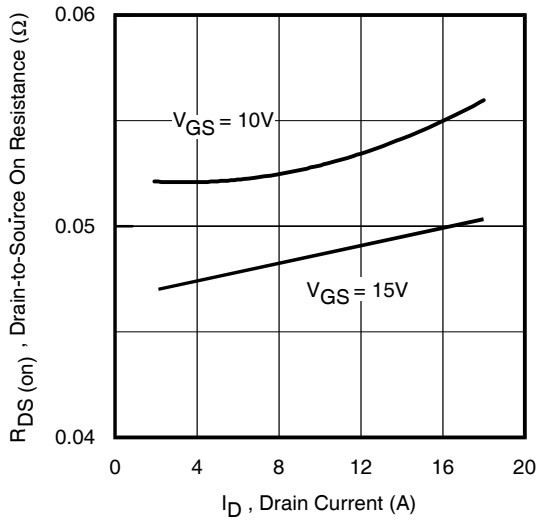


Fig 12. On-Resistance Vs. Drain Current

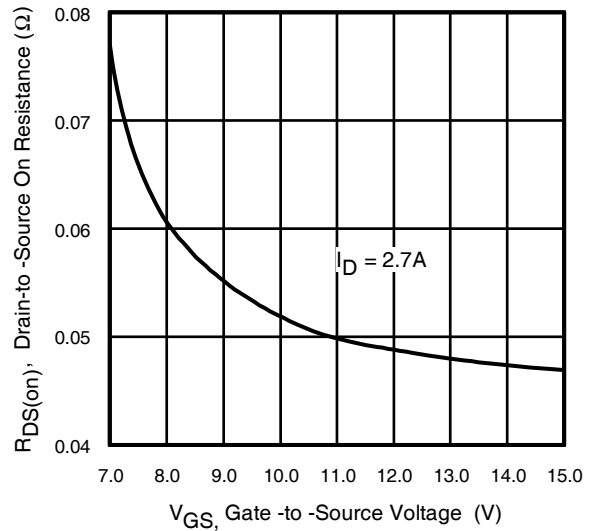


Fig 13. On-Resistance Vs. Gate Voltage

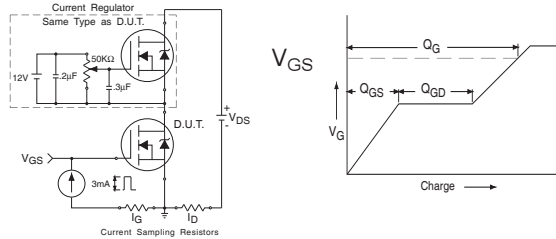


Fig 13a&b. Basic Gate Charge Test Circuit and Waveform

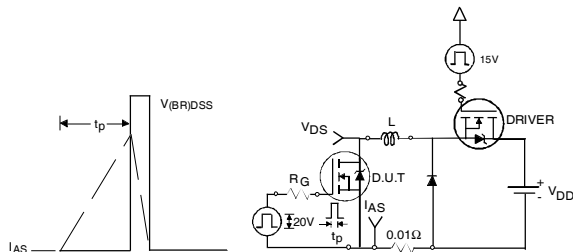


Fig 14a&b. Unclamped Inductive Test circuit and Waveforms

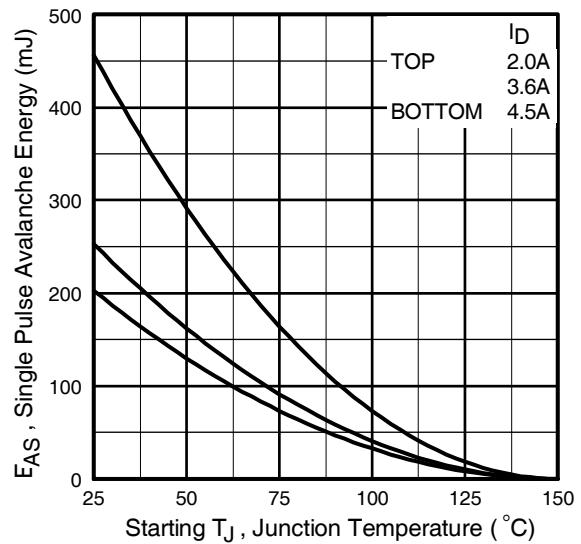


Fig 14c. Maximum Avalanche Energy Vs. Drain Current

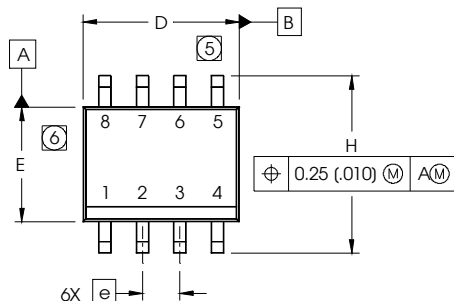
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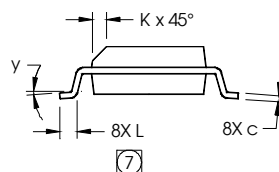
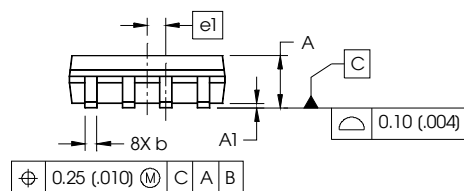
SO-8 Package Details

Dimensions are shown in millimeters (inches)

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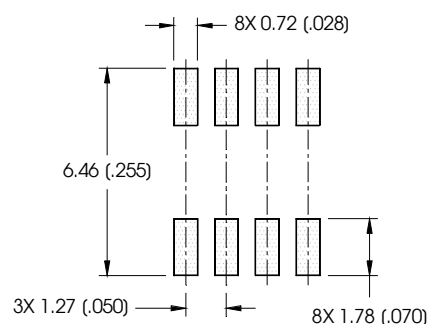
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
Al	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°



NOTES:

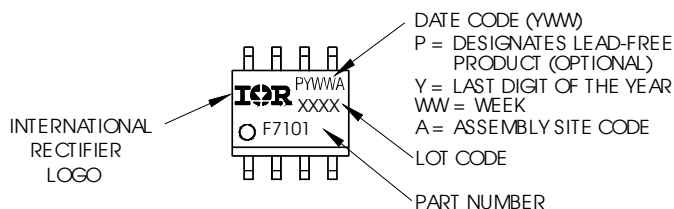
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
- ⑤ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS.
MOLD PROTRUSIONS NOT TO EXCEED 0.15 (.006).
- ⑥ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS.
MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.010).
- ⑦ DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

FOOT PRINT



SO-8 Part Marking

EXAMPLE: THIS IS AN IRF7101 (MOSFET)



Notes:

1. For an Automotive Qualified version of this part please see: <http://www.irf.com/product-info/auto/>
2. For the most current drawing please refer to IR website at <http://www.irf.com/package/>

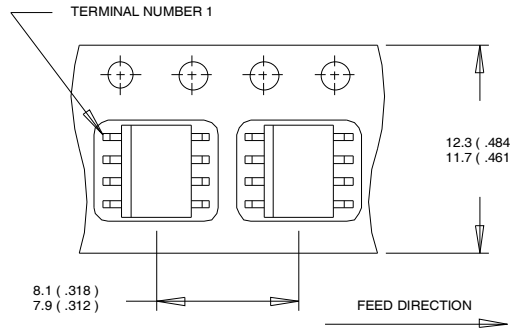
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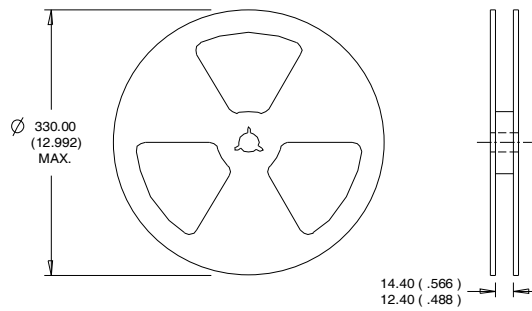
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SO-8 Tape and Reel

Dimensions are shown in millimeters (inches)



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
 2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

For the most current drawing please refer to IR website at <http://www.irf.com/package/>

END OF LIFE**Qualification Information[†]**

Qualification level	Industrial [†]	
	(per JEDEC JESD47F ^{††} guidelines)	
Moisture Sensitivity Level	SO-8	MSL1 (per JEDEC J-STD-020D ^{††})
RoHS Compliant	Yes	

[†] Qualification standards can be found at International Rectifier's web site
<http://www.irf.com/product-info/reliability>

^{††} Applicable version of JEDEC standard at the time of product release.

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting $T_J = 25^{\circ}\text{C}$, $L = 20\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 4.5\text{A}$.
- ③ Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.
- ④ When mounted on 1 inch square copper board, $t < 10\text{ sec}$

Revision History

Date	Comments
12/19/2014	• Added ordering information to reflect the End-Of-life